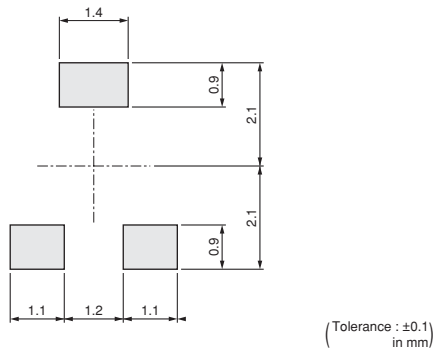


Mounting

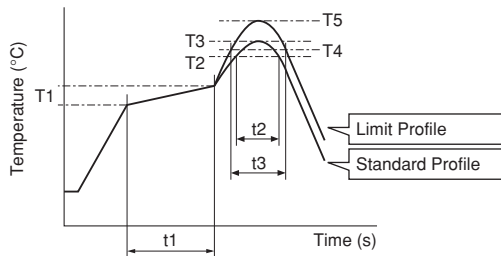
Land Pattern



Soldering Profile

Reflow Soldering Profile

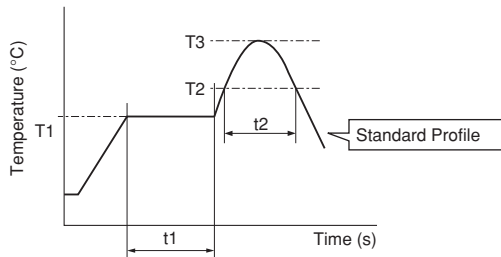
1. Soldering profile for lead free solder (96.5Sn/3.0Ag/0.5Cu)



Series	Standard Profile						Limit Profile					
	Pre-heating		Heating		Peak Temperature (T3)	Cycle of Reflow	Pre-heating		Heating		Peak Temperature (T5)	Cycle of Reflow
	Temp. (T1)	Time (t1)	Temp. (T2)	Time (t2)			Temp. (T1)	Time (t1)	Temp. (T4)	Time (t3)		
°C	sec.	°C	sec.	°C	Time	°C	sec.	°C	sec.	°C	Time	
PVG3	150 to 180	60 to 120	220	30 to 60	245±3	1	150 to 180	60 to 120	230	30 to 50	260 +5/-0	2

2. Soldering profile for Eutectic solder (63Sn/37Pb)

(Limit profile: refer to 1)



Series	Standard Profile					
	Pre-heating		Heating		Peak Temperature (T3)	Cycle of Reflow
	Temp. (T1)	Time (t1)	Temp. (T2)	Time (t2)		
°C	sec.	°C	sec.	°C	Time	
PVG3	150	60 to 120	183	30	230	1

Soldering Iron

Series	Standard Condition			
	Temperature of Soldering Iron Tip	Soldering Time	Soldering Iron Power Output	Cycle of Soldering Iron
	°C	sec.	W	Time
PVG3	350±10	3 max.	30 max.	1